Switching Diodes 1N6638 Series

1N6638, 1N6639, 1N6640, 1N6641, 1N6642, 1N6643, 1N6638U & US, 1N6639U & US, 1N6640U & US, 1N6641U & US 1N6642U & US, 1N6643U & US

Features

- Available in JAN, JANS, JANTX, JANTXV per MIL-PRF-19500/578 & /609
- Switching Diodes
- Non-Cavity Glass Plackage
- Category I Metallurgically Bonded

Maximum Ratings

Thermal Resistance:

($R_{\Theta JEC}$): U & US 40 °C/W maximum at L = 0" See Figure 6

A passion for performance.

(R_{Θ JL}): Leaded 150 °C/W maximum at L = .375" See Figure 7

Thermal Impedance: (Z_{OJX}): 25 °C/W maximum

Electrical Specifications @ $TA = + 25 \ ^{\circ}C$ (Unless Otherwise Specified)

Types	V _{BR} @ I _R		VWRM		/ t _{fr} @ 200 mA	C _{T1} V _R =0 V	C _{T2} V _R =1.5 V	t_{rr} I _R = 10mA I _F = 10mA	I_{R1} $V_{R}=V_{RWM}$ $T_{A} = 150^{\circ}C$	I_{R2} $V_{R}=20V$ $T_{A} = 150^{\circ}C$	I _{R3} V _R =20V	$V_{R} = V_{RWM}$
	V(pk)	μA	V(pk)	V _{FR} V(pk)	t _{fr} ns	pF	pF	ns	nA dc	nA dc	μA dc	μA dc
1N6638, U & US	150	100	125	5.0	20	2.5	2.0	4.5	35	500	50	100
1N6639, U & US	100	10	75	5.0	10	2.5	-	4.0	-	100	-	90
1N6640, U & US	75	10	50	5.0	10	2.5	-	4.0	-	100	-	90
1N6641, U & US	75	10	50	5.0	10	3.0	-	5.0	-	100	-	90
1N6642, U & US	100	100	75	5.0	20	5.0	2.8	5.0	25	500	50	100
1N6643, U & US	75	100	50	5.0	20	5.0	2.8	6.0	50	500	75	100

TYPES	V _F	@ I _F	V _{F2} @ I _F T _A = -55°C	۱ _F
	V dc (min)	V dc (max)	V dc (max)	mA (pulsed)
1N6638, U & US	-	1.1 0.8	1.2 -	200 10
1N6639, U & US	-	1.2	1.3	500
1N6640, U & US	0.54 0.76 0.82 0.87	0.62 0.86 0.92 1.0	- - - 1.1	1 50 100 200
1N6641, U & US	-	1.1	1.2	200
1N6642, U & US	-	0.8 1.2	- 1.2	10 100
1N6643, U & US	-	0.8 1.2	- 1.4	10 100





Outline Drawing



Symbol	Inc	hes	Millin	Notes	
	Min	Max	Min	Max	
BD	.056	.080	1.42	2.03	2
BL	.130	.180	3.30	4.57	
LD	.018	.022	.046	0.56	3
LL	1.00	1.50	25.40	38.10	

LEADED DESIGN DATA

CASE: D-5D, Hermetically sealed glass case, per MIL-PRF-19500/578 & /609 LEAD FINISH: Tin/Lead LEAD MATERIAL: Copper clad steel POLARITY: Cathode end is banded. PACKAGE WEIGHT: 0.150g





	Dimensions						
Symbol	Inc	hes	Millimeters				
	Min	Max	Min	Max			
D	.070	.085	1.78	2.16			
В	.165	.195	4.19	4.95			
ECT	.019	.028	.048	0.71			
S	.003		0.08				

U & US DESIGN DATA

CASE: D-5D, Hermetically sealed glass case, per MIL-PRF-19500/578 & /609 LEAD FINISH: Tin/Lead END CAP MATERIAL (U, US): Copper

POLARITY: Cathode end is banded.

PACKAGE WEIGHT: 0.095g

MOUNTING SURFACE SELECTION: The Axial Coefficient of Expansion (COE) of this device is approximately +4PPM/°C. The COE of the Mounting Surface System should be selected to provide a suitable match with this device.

NOTES:

- 1. Dimensions are in inches. Millimeters are given for general information only.
- 2. Dimension BD shall be measured at the largest diameter.
- The specified lead diameter applies in the zone between .050 inch (1.27 mm) from the diode body to the end of the lead. Outside of this zone lead shall not exceed BD.
- 4. In accordance with ASME y14.5M, diameters are equivalent to Φx symbology.
- 5. U-suffix parts are structurally identical to the US-suffix parts.

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NOTES:

- 1. All devices are capable of operating at ≤ TJ specified on this curve. Any parallel line to this curve will intersect the appropriate current for the desired maximum TJ allowed.
- 2. Derate design curve constrained by the maximum junction temperatures and current rating specified. (See 1.3.)
- 3. Derate design curve chosen at $TJ \le 150^{\circ}C$, where the maximum temperature of electrical test is performed.
- 4. Derate design curves chosen at TJ ≤ 125°C, and 110°C to show current rating where most users want to limit TJ intheir application.

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FIGURE 6. <u>Thermal impedance –</u> <u>all U and US devices</u>.

 $R_{\Theta JL}$ = 40°C/W

 $Z_{\Theta JX} = 25^{\circ}C/W$ maximum at $t_H = 10$ ms

Lead spacing = .375 inch mounted to an infinite heat dissipater



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Suggested Minimum Footprints D-5D (D-BODY) U, US DIODES



FIGURE 8

NOTES:

- 1. Dimensions are in inches / mm.
- 2. The dimensions listed will match the device terminals based on worst-case package outline drawings and assuming accuracy of device placements is within 0.005 inches. Footprints also provide for solder filets at the outer ends of the device at least as wide as the terminals.
- 3. F designates recommendation to fill unused area with an extended copper pad in order to reduce the CTE difference between the device and the PC board. The extended area may be3 coated with a solder mask. the width of F depends upon your PCB design rules.

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